280372-2 - ACTIVE

AMPMODU | AMPMODU Headers

TE Internal #: 280372-2 PCB Mount Header, Vertical, Board-to-Board, 6 Position, 2.54 mm [. 1 in] Centerline, Partially Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: 6

Number of Rows: 1

Features

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Product Type Features

Connector Shape	Rectangular		
PCB Connector Assembly Type	PCB Mount Header		
Connector System	Board-to-Board		
Header Type	Partially Shrouded		
Sealable	No		
Connector & Contact Terminates To	Printed Circuit Board		
Configuration Features			
Connector Contact Load Condition	Fully Loaded		
Connector Contact Load Condition PCB Mount Orientation	Fully Loaded Vertical		
PCB Mount Orientation	Vertical		
PCB Mount Orientation Number of Positions	Vertical		
PCB Mount OrientationNumber of PositionsNumber of Rows	Vertical		

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Body Features

Connector Profile	Standard			
Primary Product Color	Black			
Contact Features				
Contact Mating Area Length	6.6 mm[.259 in]			
Mating Square Post Dimension	.63 mm[.025 in]			
PCB Contact Termination Area Plating Material Thickness	2.5 μm[98.42 μin]			
Contact Layout	Inline			
Contact Underplating Material Thickness	1.27 μm[50 μin]			
Contact Shape & Form	Square			
Contact Mating Area Plating Material Finish	Bright			
Contact Underplating Material	Nickel			
PCB Contact Termination Area Plating Material	Tin			
Contact Base Material	Brass			
Contact Mating Area Plating Material	Gold			
Contact Mating Area Plating Material Thickness	.381 μm[15 μin]			
Contact Type	Pin			
Contact Current Rating (Max)	3 A			

Termination Features

Termination Post & Tail Length	3.5 mm[.138 in]				
Termination Method to PCB	Through Hole - Solder				
Mechanical Attachment					
Mating Retention	With				
Panel Mount Feature	Without				
Mating Alignment	With				
Mating Alignment Type	Polarization				
PCB Mount Retention	Without				
PCB Mount Alignment	Without				
Connector Mounting Type	Board Mount				
Housing Features					
Centerline (Pitch)	2.54 mm[.1 in]				
Housing Material	Flame Retardant Thermoplastic				

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Dimensions

Connector Length	17.8 mm[.7 in]			
Connector Height	12.6 mm[.496 in]			
Connector Width	5 mm[.197 in]			
Row-to-Row Spacing	2.54 mm[.1 in]			
Usage Conditions				
Housing Temperature Rating	Standard			
Operating Temperature Range	-40 – 80 °C[-40 – 176 °F]			
Operation/Application				
Circuit Application	Power & Signal			
Industry Standards				
Industry Standard	IEC			
UL Flammability Rating	UL 94V-0			
Packaging Features				
Packaging Quantity	1000			
Packaging Method	Box			

Product Compliance

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Not Low Halogen - contains Br or Cl > 900 ppm.
Solder Process Capability	Wave solder capable to 265°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products

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will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-onreach

Compatible Parts

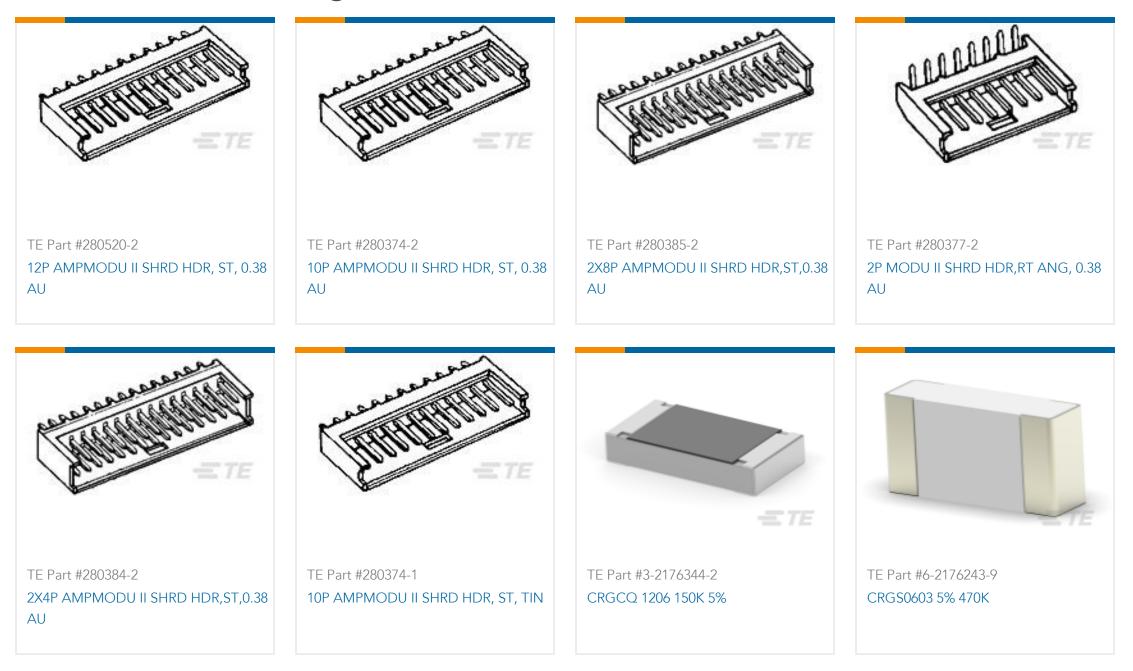


Also in the Series AMPMODU Headers



		& Housings(5)

Customers Also Bought



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Documents

Product Drawings 6P AMPMODU II SHRD HDR, ST, 0.38AU

English

CAD Files

3D PDF

3D

Customer View Model ENG_CVM_CVM_280372-2_U_c-280372-2-u.2d_dxf.zip

English

Customer View Model ENG_CVM_CVM_280372-2_U_c-280372-2-u.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_280372-2_U_c-280372-2-u.3d_stp.zip

English

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